

- Members of the Texas Instruments *Widebus™ Family*
- State-of-the-Art *EPIC-IIIB™ BiCMOS Design* Significantly Reduces Power Dissipation
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- High-Drive Outputs ($-32\text{-mA } I_{OH}$, $64\text{-mA } I_{OL}$)
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model ($C = 200 \text{ pF}$, $R = 0$)
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

description

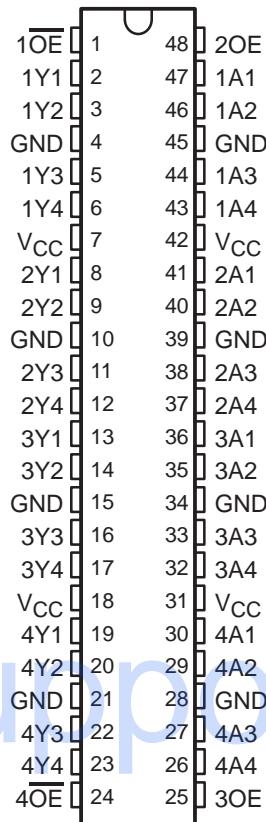
The 'ABT16241A devices are 16-bit buffers and line drivers designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

These devices can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. These devices provide true outputs and complementary output-enable (OE and \overline{OE}) inputs.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver. OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

The SN54ABT16241A is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ABT16241A is characterized for operation from -40°C to 85°C .

SN54ABT16241A . . . WD PACKAGE
SN74ABT16241A . . . DGG, DGV, OR DL PACKAGE
(TOP VIEW)



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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

SN54ABT16241A, SN74ABT16241A

16-BIT BUFFERS/DRIVERS

WITH 3-STATE OUTPUTS

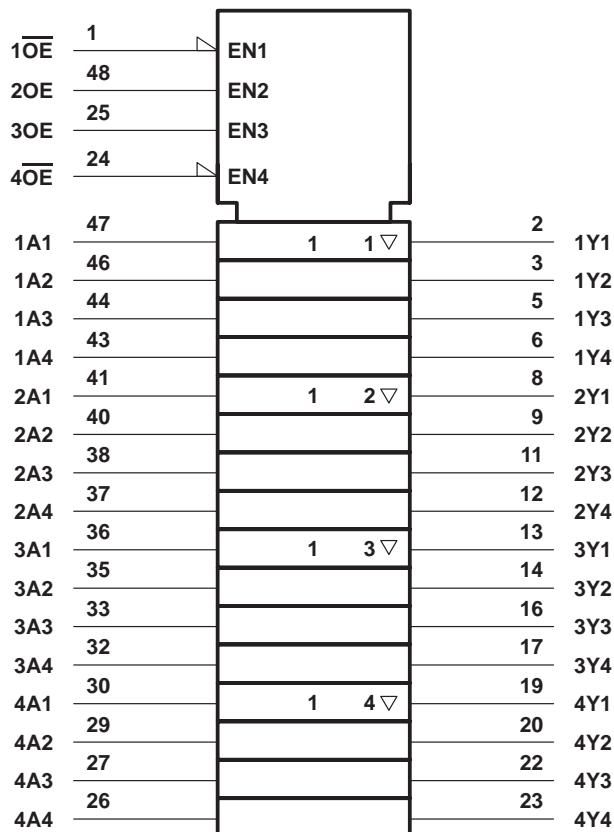
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FUNCTION TABLES

INPUTS		OUTPUTS 1Y, 4Y
$\overline{1OE}$, 4 \overline{OE}	1A, 4A	
L	H	H
L	L	L
H	X	Z

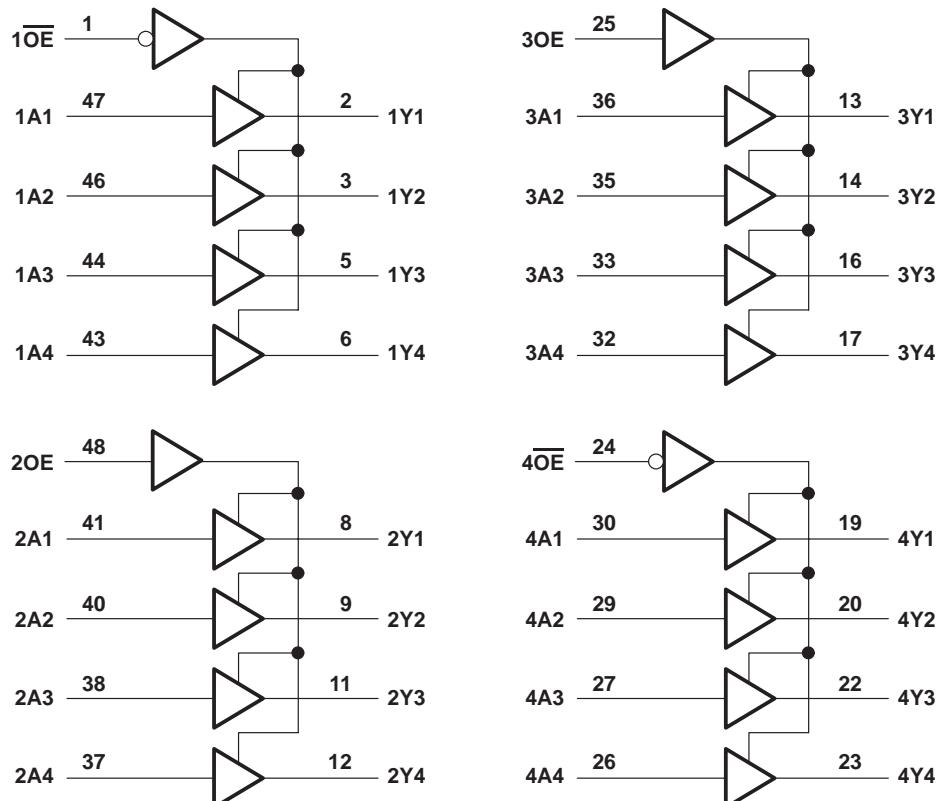
INPUTS		OUTPUTS 2Y, 3Y
2OE, 3OE	2A, 3A	
H	H	H
H	L	L
L	X	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	-0.5 V to 7 V
Input voltage range, V_I (see Note 1)	-0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O	-0.5 V to 5.5 V
Current into any output in the low state, I_O :	SN54ABT16241A	96 mA
	SN74ABT16241A	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	-18 mA
Output clamp current, I_{OK} ($V_O < 0$)	-50 mA
Package thermal impedance, θ_{JA} (see Note 2):	DGG package	89°C/W
	DGV package	93°C/W
	DL package	94°C/W
Storage temperature range, T_{Stg}	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JEDEC 51.

**SN54ABT16241A, SN74ABT16241A
16-BIT BUFFERS/DRIVERS
WITH 3-STATE OUTPUTS**

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recommended operating conditions (see Note 3)

		SN54ABT16241A		SN74ABT16241A		UNIT
		MIN	MAX	MIN	MAX	
V _{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V _{IH}	High-level input voltage	2		2		V
V _{IL}	Low-level input voltage		0.8		0.8	V
V _I	Input voltage	0	V _{CC}	0	V _{CC}	V
I _{OH}	High-level output current		-24		-32	mA
I _{OL}	Low-level output current		48		64	mA
Δt/Δv	Input transition rise or fall rate	Outputs enabled		10	10	ns/V
T _A	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	T _A = 25°C			SN54ABT16241A		SN74ABT16241A		UNIT
		MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V _{IK}	V _{CC} = 4.5 V, I _I = -18 mA		-1.2		-1.2		-1.2		V
V _{OH}	V _{CC} = 4.5 V, I _{OH} = -3 mA	2.5			2.5		2.5		V
	V _{CC} = 5 V, I _{OH} = -3 mA	3			3		3		
	V _{CC} = 4.5 V	I _{OH} = -24 mA	2		2			2	
		I _{OH} = -32 mA	2*						
V _{OL}	V _{CC} = 4.5 V	I _{OL} = 48 mA		0.55		0.55			V
		I _{OL} = 64 mA		0.55*				0.55	
V _{hys}		100							mV
I _I	V _{CC} = 5.5 V, V _I = V _{CC} or GND		±1		±1		±1		µA
I _{OZH}	V _{CC} = 5.5 V, V _O = 2.7 V		10		10		10		µA
I _{OZL}	V _{CC} = 5.5 V, V _O = 0.5 V		-10		-10		-10		µA
I _{off}	V _{CC} = 0, V _I or V _O ≤ 4.5 V		±100				±100		µA
I _{CEX}	V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high		50		50		50	µA
I _O ‡	V _{CC} = 5.5 V, V _O = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA
I _{CC}	V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND	Outputs high		3		3		3	mA
		Outputs low		34		34		34	
		Outputs disabled		3		3		3	
ΔI _{CC} §	Data inputs	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND	Outputs enabled		1	1.5	1		mA
			Outputs disabled		0.05	1	0.05		
C _i	Control inputs	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND		1.5		1.5		1.5	
		V _O = 2.5 V or 0.5 V		3.5					pF
C _o		V _O = 2.5 V or 0.5 V		7.5					pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.

† All typical values are at V_{CC} = 5 V.

‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.



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**SN54ABT16241A, SN74ABT16241A
16-BIT BUFFERS/DRIVERS
WITH 3-STATE OUTPUTS**

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT16241A			UNIT	
			$V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$				
			MIN	TYP	MAX		
t_{PLH}	A	Y	0.9	2.7	3.4	0.9	3.8
t_{PHL}			0.9	2.7	3.9	0.9	4.6
t_{PZH}	OE or \overline{OE}	Y	1.2	3.3	4.2	1.2	5.1
t_{PZL}			1.3	3.4	5.9	1.3	7
t_{PHZ}	OE or \overline{OE}	Y	1.5	4.1	5.5	1.5	7
t_{PLZ}			1.7	3.6	5.1	1.7	5.7

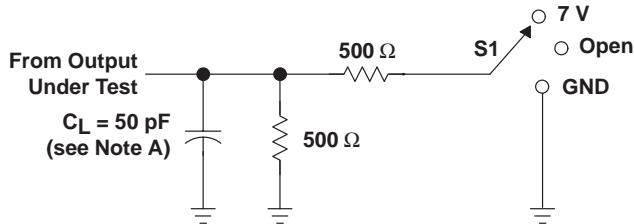
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT16241A			UNIT	
			$V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$				
			MIN	TYP	MAX		
t_{PLH}	A	Y	1	2.7	3.4	1	3.7
t_{PHL}			1	2.7	3.9	1	4.5
t_{PZH}	OE or \overline{OE}	Y	1.2	3.3	4.2	1.2	5
t_{PZL}			1.3	3.4	5.9	1.3	6.9
t_{PHZ}	OE or \overline{OE}	Y	1.5	4.1	5.2	1.5	6.2
t_{PLZ}			1.7	3.6	5.1	1.7	5.6

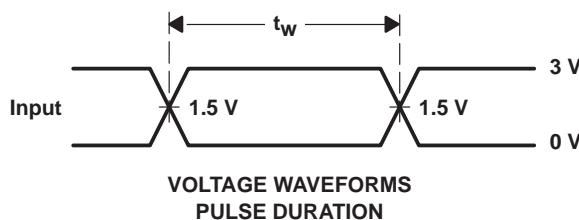
**SN54ABT16241A, SN74ABT16241A
16-BIT BUFFERS/DRIVERS
WITH 3-STATE OUTPUTS**

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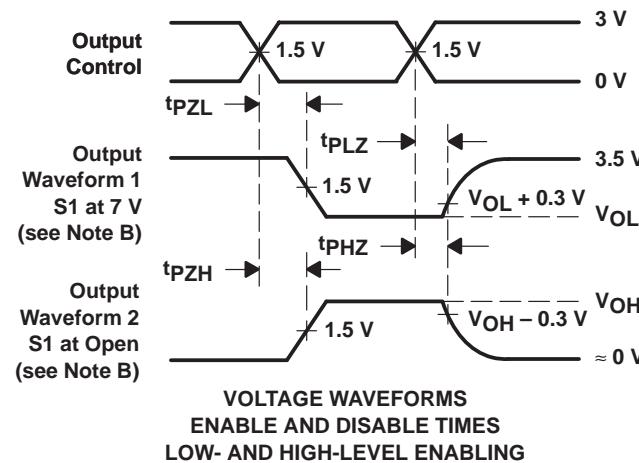
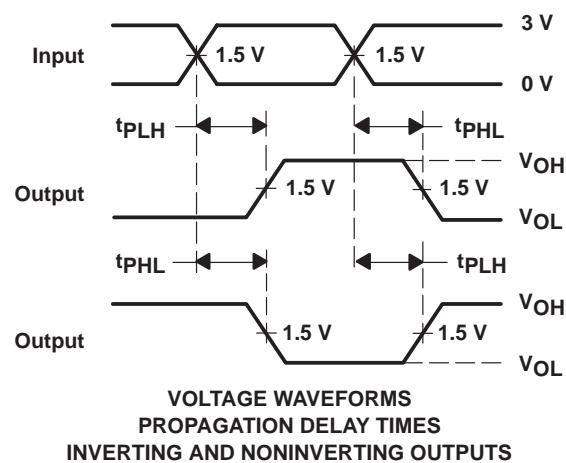
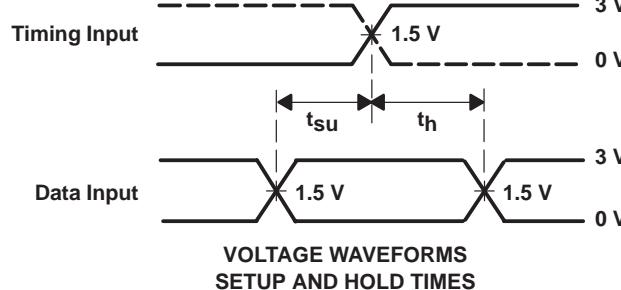
PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT



TEST	S1
tPLH/tPHL	Open
tPLZ/tPZL	7 V
tPHZ/tPZH	Open



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
 - D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9450101QXA	ACTIVE	CFP	WD	48	1	TBD	Call TI	Level-NC-NC-NC
74ABT16241ADGGRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ABT16241ADGVRE4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16241ADGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16241ADGVR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16241ADL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16241ADLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54ABT16241AWD	ACTIVE	CFP	WD	48	1	TBD	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

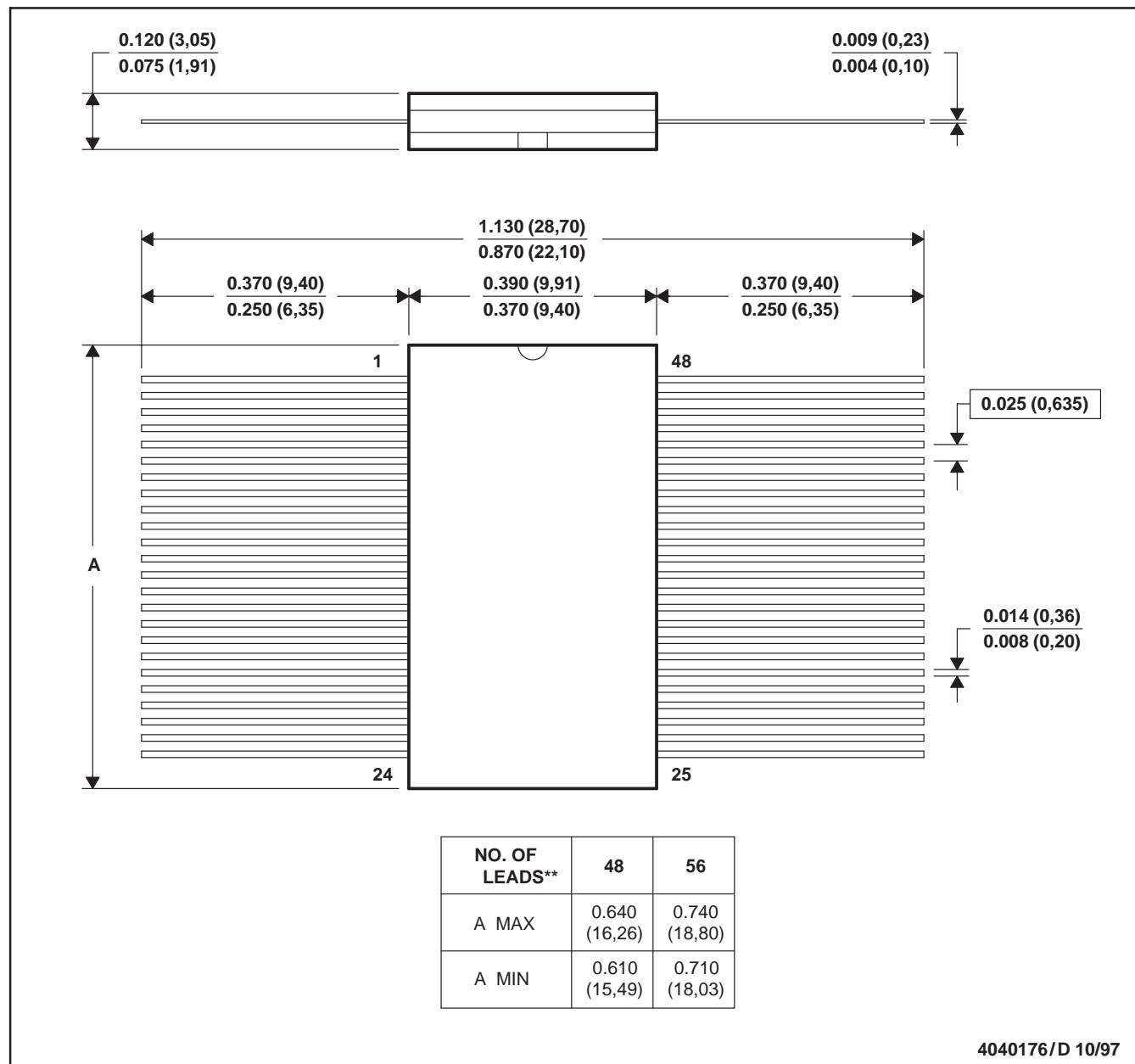
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WD (R-GDFP-F**)

CERAMIC DUAL FLATPACK

48 LEADS SHOWN

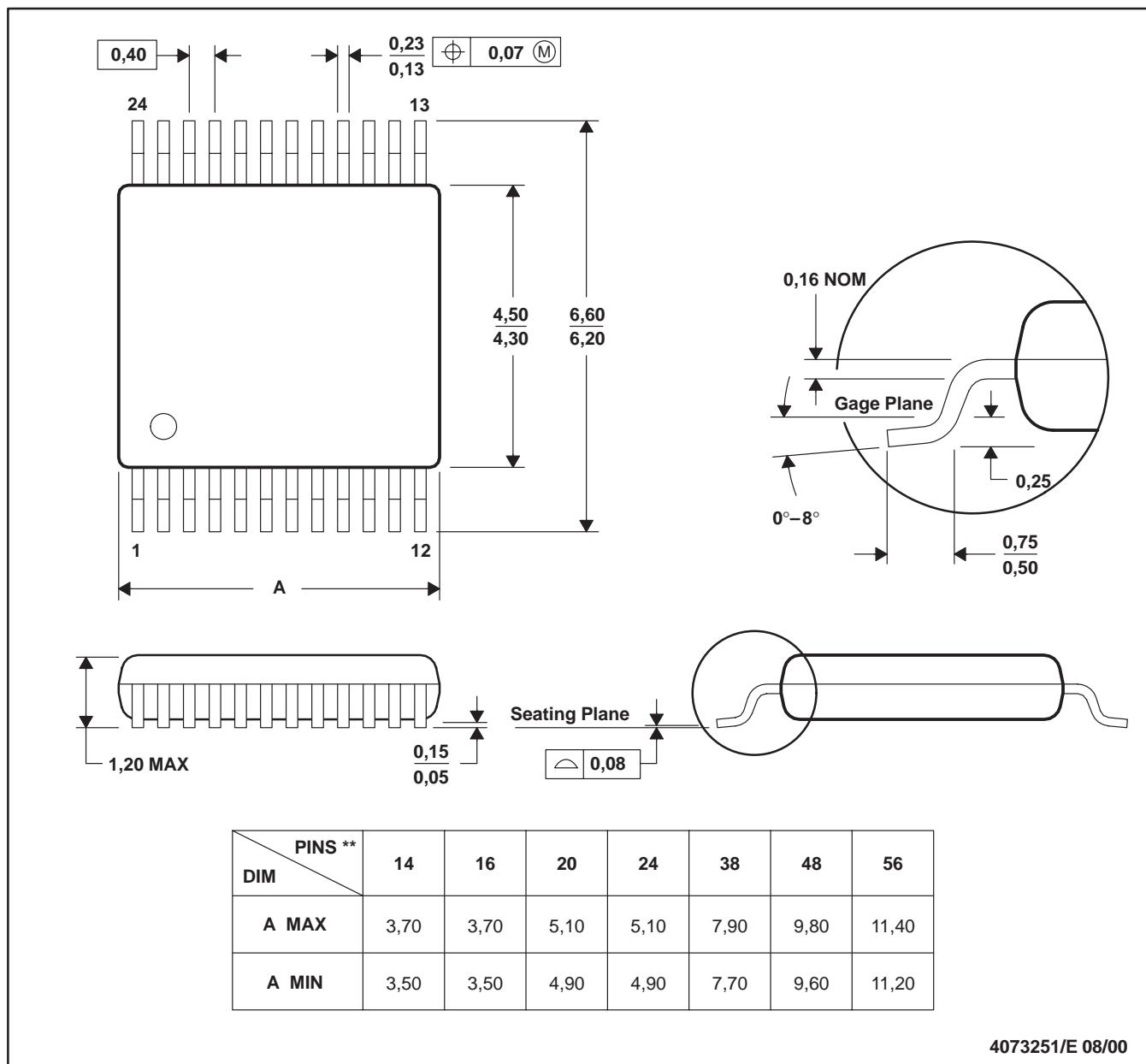


- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a ceramic lid using glass frit.
 D. Index point is provided on cap for terminal identification only
 E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA
 GDFP1-F56 and JEDEC MO-146AB

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN

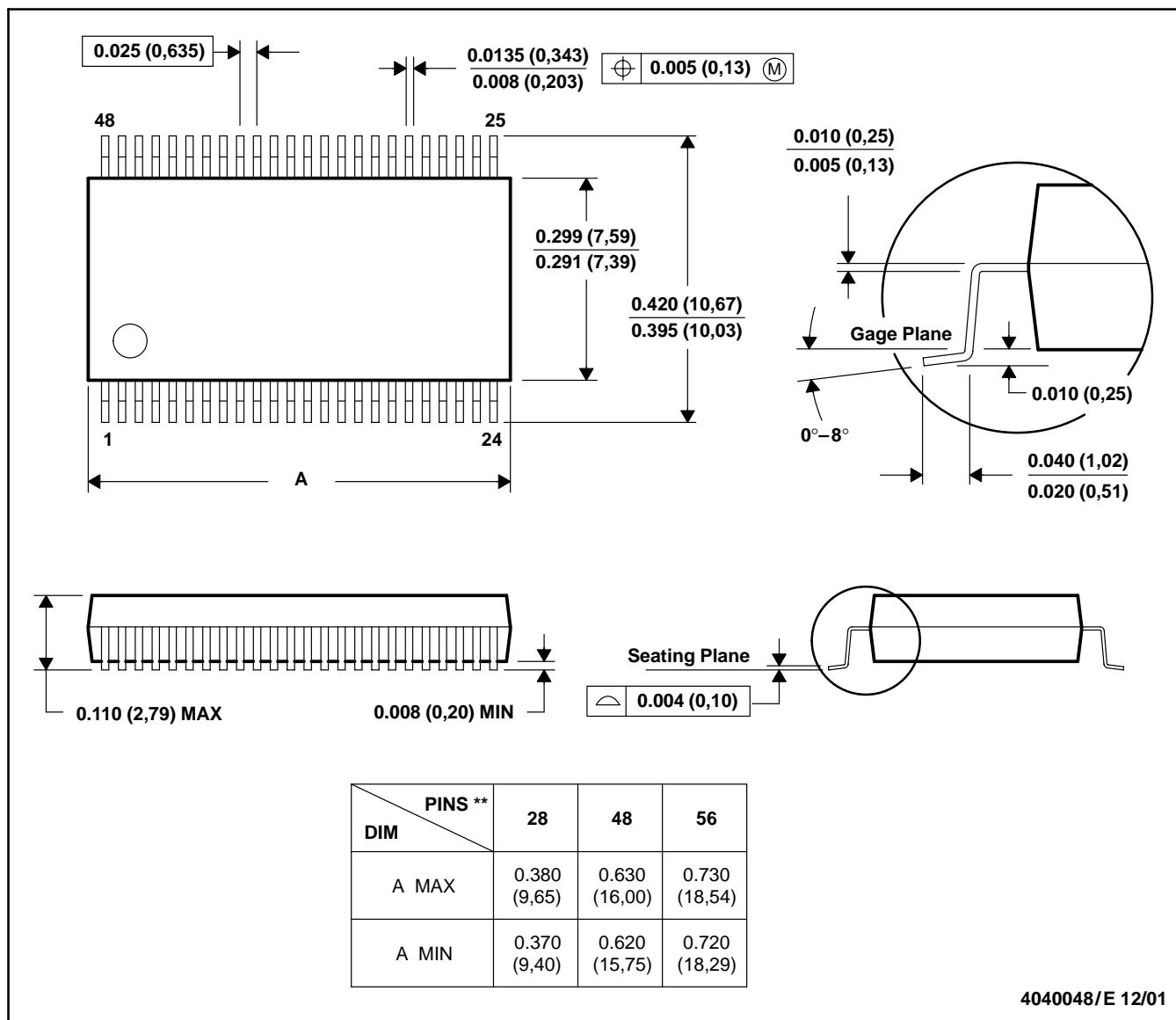


- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 - D. Falls within JEDEC: 24/48 Pins – MO-153
14/16/20/56 Pins – MO-194

DL (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN

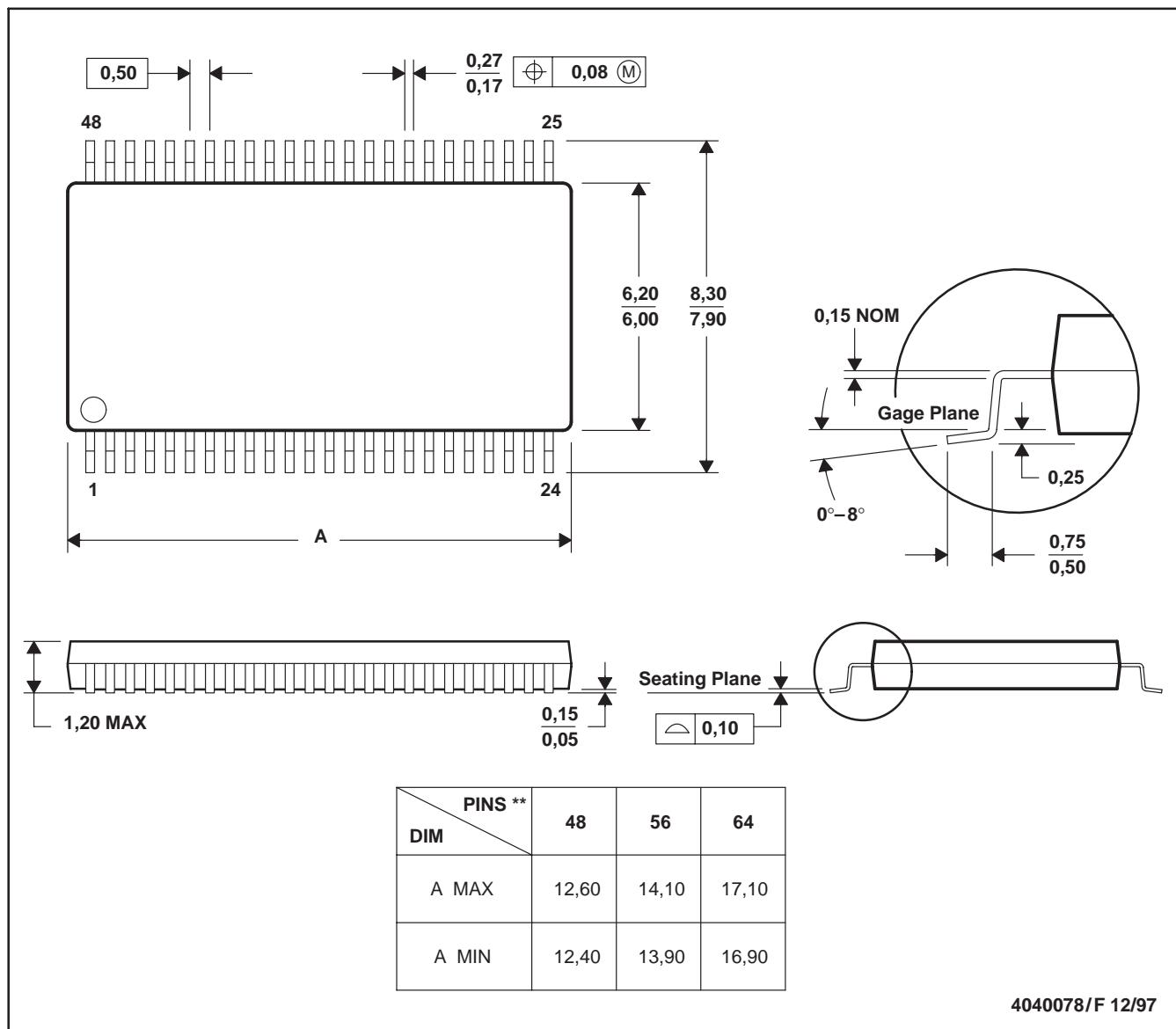


- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. Falls within JEDEC MO-118

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
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driver. OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

The SN54ABT16241A is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ABT16241A is characterized for operation from -40°C to 85°C.

Pricing/Packaging/CAD Design Tools/Samples

			Price	Packaging			CAD Design Tools	Samples
Device	Status	Temp (°C)	Budget Price (\$US) QTY	Industry Standard (TI Pkg) Pins	Top Side Marking	Standard Pack Quantity	Footprints	Samples
74ABT16241ADGGRE4	ACTIVE	-40 to 85	0.88 1KU	TSSOP (DGG) 48	View	2000	<input type="checkbox"/>	Purchase Samples
74ABT16241ADGVRE4	ACTIVE	-40 to 85	0.88 1KU	TVSOP (DGV) 48	View	2000	<input type="checkbox"/>	Purchase Samples
SN74ABT16241ADGGR	ACTIVE	-40 to 85	0.88 1KU	TSSOP (DGG) 48	View	2000	<input type="checkbox"/>	Purchase Samples
SN74ABT16241ADGVR	ACTIVE	-40 to 85	0.88 1KU	TVSOP (DGV) 48	View	2000	<input type="checkbox"/>	Purchase Samples
SN74ABT16241ADL	ACTIVE	-40 to 85	0.88 1KU	SSOP (DL) 48	View	25	<input type="checkbox"/>	Purchase Samples
SN74ABT16241ADLR	ACTIVE	-40 to 85	0.88 1KU	SSOP (DL) 48	View	1000	<input type="checkbox"/>	Purchase Samples

Inventory

		TI Inventory Status			Reported Distributor Inventory			
74ABT16241ADGGRE4		As of 9:18 AM GMT, 25 Nov 2005			As of 9:18 AM GMT, 25 Nov 2005			
		In Stock	In Progress QTY Date	Lead Time	Region	Company	In Stock	Purchase
		0*		14 Weeks	None Reported View Distributors			
74ABT16241ADGVRE4		As of 9:18 AM GMT, 25 Nov 2005			As of 9:18 AM GMT, 25 Nov 2005			
		In Stock	In Progress QTY Date	Lead Time	Region	Company	In Stock	Purchase
		0*	378 3 Feb	14 Weeks	None Reported View Distributors			
			6 10 Feb					
SN74ABT16241ADGGR		As of 9:18 AM GMT, 25 Nov 2005			As of 9:18 AM GMT, 25 Nov 2005			
		In Stock	In Progress QTY Date	Lead Time	Region	Company	In Stock	Purchase
		0*		14 Weeks	Americas	DigiKey	>1k	<input type="text"/>
					Europe	Avnet-SILICA	>1k	<input type="text"/>
SN74ABT16241ADGVR		As of 9:18 AM GMT, 25 Nov 2005			As of 9:18 AM GMT, 25 Nov 2005			
		In Stock	In Progress QTY Date	Lead Time	Region	Company	In Stock	Purchase
		0*	378 3 Feb	14 Weeks	Americas	DigiKey	>1k	<input type="text"/>
			6 10 Feb					
SN74ABT16241ADL		As of 9:18 AM GMT, 25 Nov 2005			As of 9:18 AM GMT, 25 Nov 2005			
		In Stock	In Progress QTY Date	Lead Time	Region	Company	In Stock	Purchase
		0*	600 8 Dec	8 Weeks	Americas	Arrow	93	<input type="text"/>
			>10k 6 Feb			DigiKey	269	<input type="text"/>
					Europe	Spoerle	279	<input type="text"/>
SN74ABT16241ADLR		As of 9:18 AM GMT, 25 Nov 2005			As of 9:18 AM GMT, 25 Nov 2005			
		In Stock	In Progress QTY Date	Lead Time	Region	Company	In Stock	Purchase
		0*	>10k 6 Feb	11 Weeks	None Reported View Distributors			

* Our information is updated daily, so please check back with us soon if this does not meet your needs. You may also contact your [TI Authorized Distributor](#), including those [listed above](#), for real time stock information.

** Lead time information is not available at this time. However, our information is updated daily so please check back with us soon. Please contact your preferred [TI Authorized Distributor](#) for additional information.

Quality & Lead (Pb)-Free Data

Device	Eco Plan*	Lead/Ball Finish	MSL Rating/Peak Reflow	Details	MTBF/FIT Rate
74ABT16241ADGGRE4	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	View	View
74ABT16241ADGVRE4	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	View	View
SN74ABT16241ADGGR	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	View	View
SN74ABT16241ADGVR	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	View	View
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